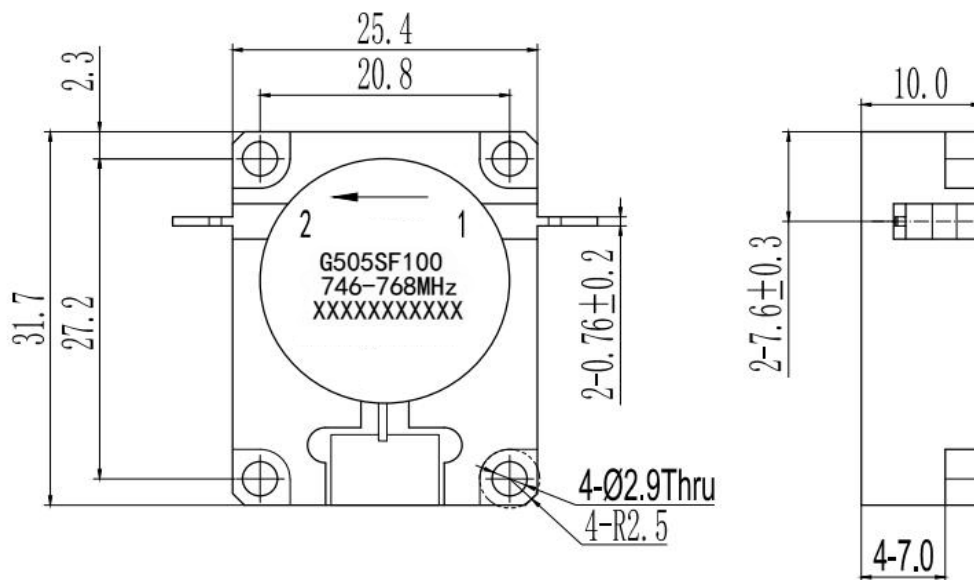


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G505S [729-746]MHz	0.729	0.746	0.738	0.017	25	0.25	1.12	100	-70
G505S [746-768]MHz	0.746	0.768	0.757	0.022	25	0.25	1.12	100	-70
G505S [758-803]MHz	0.758	0.803	0.781	0.045	25	0.25	1.12	100	-70
G505S [791-821]MHz	0.791	0.821	0.805	0.030	25	0.25	1.12	100	-70
G505S [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.25	1.12	100	-70
G505S [1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.12	100	-70
G505S [2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.25	1.12	100	-70